2002 052488

29 AUG 2002

162162

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization
International Bureau

(43) International Publication Date
4 October 2001 (04.10.2001)

PCT

(10) International Publication Number
WO 01/73841 A3

(51) International Patent Classification[7]: H01L 21/768, 23/528, 23/532

(21) International Application Number: PCT/EP01/02797

(22) International Filing Date: 13 March 2001 (13.03.2001)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
09/525,095 14 March 2000 (14.03.2000) US

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(81) Designated States (national): AE, AG, AL, AM, AT (utility model), AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CR, CU, CZ, DE, DK, DM, DZ, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TR, TT, TZ, UA, UG, UZ, VN, YU, ZA, ZW.

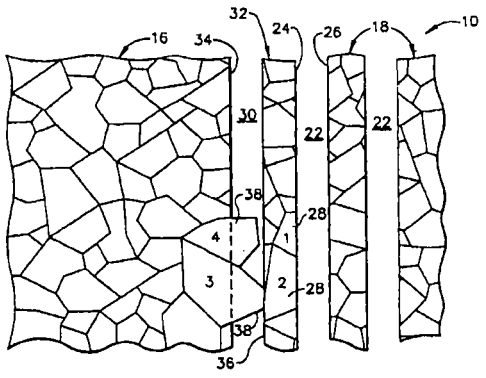
(84) Designated States (regional): ARIPO patent (GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GW, ML, MR, NE, SN, TD, TG).

Published:
— with international search report

(88) Date of publication of the international search report:
7 March 2002

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: METHOD OF PREVENTING BRIDGING BETWEEN POLYCRYSTALLINE MICRO-SCALE FEATURES



(57) Abstract: A method of preventing or at least reducing the likelihood of bridging (20) between adjacent micro-scale polycrystalline structures, and particularly to reducing electrical shorting between adjacent metallization lines of a microcircuit. The method generally entails forming a multilayer structure that comprises a polycrystalline layer (12) and at least one constraining layer (14), and then patterning the multilayer structure to yield a first line (16) and a second line (18) that is narrower in width than the first line. The first line has a patterned edge (24) that is spaced apart from a patterned edge (26) of the second line, so that the first and second lines are electrically insulated from each other. One or more features associated with the first line are then formed that prevent bridging between the first and second lines if excessive lateral grain growth subsequently occurs along the patterned edge of the first line.

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